

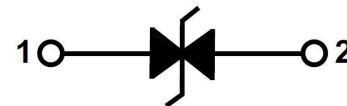
SE05N6C01GZ
Features

- ◆ Protects one data or I/O line
- ◆ Low capacitance
- ◆ Low clamping voltage
- ◆ IEC 61000-4-2, level 4
- ◆ IEC 61000-4-2 (ESD), > ±15KV (air),
> ±8KV (contact)

DFN1006

Applications

- ◆ Cellular Handsets & Accessories
- ◆ Digital Visual Interface (DVI)
- ◆ RF Circuits
- ◆ Display Port
- ◆ USB Ports
- ◆ MDDI Ports
- ◆ PCI Express

Functional Diagram

Mechanical Characteristics

- ◆ DFN1006 (1.0x0.6x0.5mm) Package
- ◆ Weight 0.5 Milligrams (Approximate)
- ◆ Quantity Per Reel : 10,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free

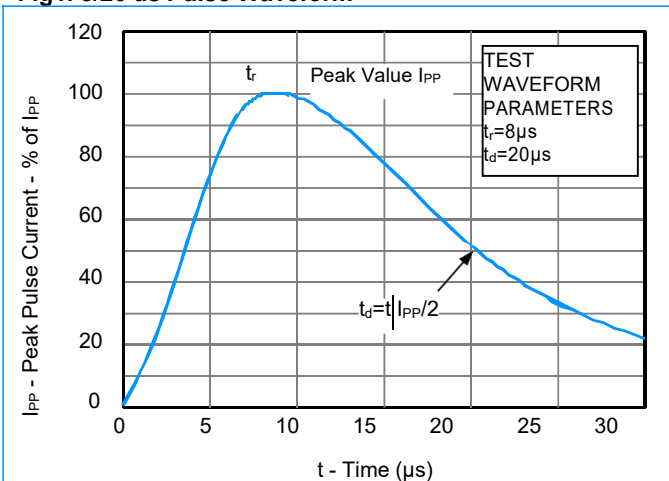
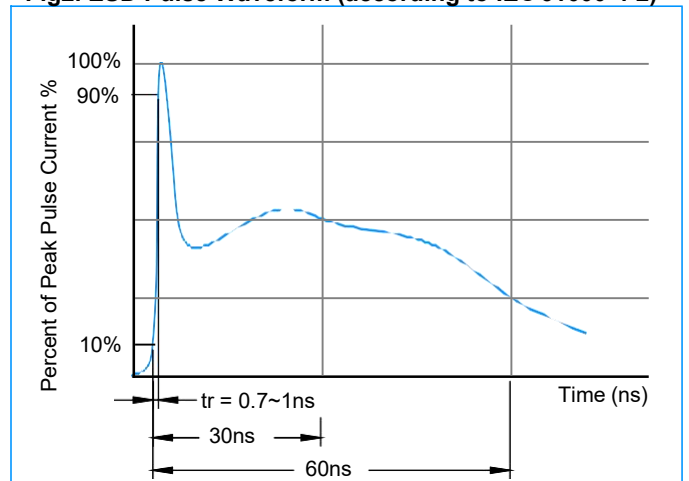
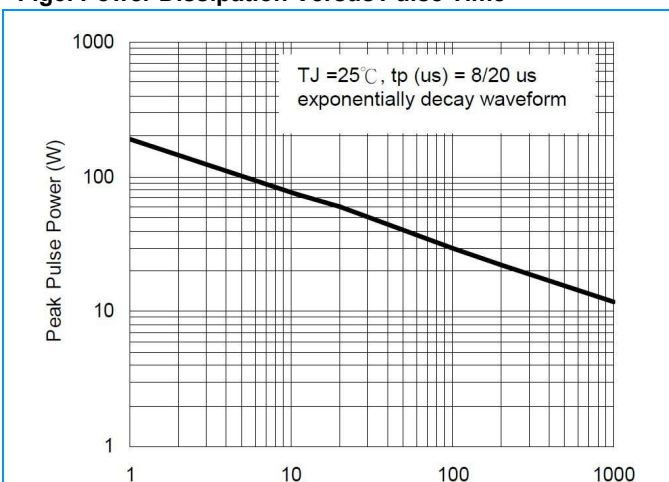
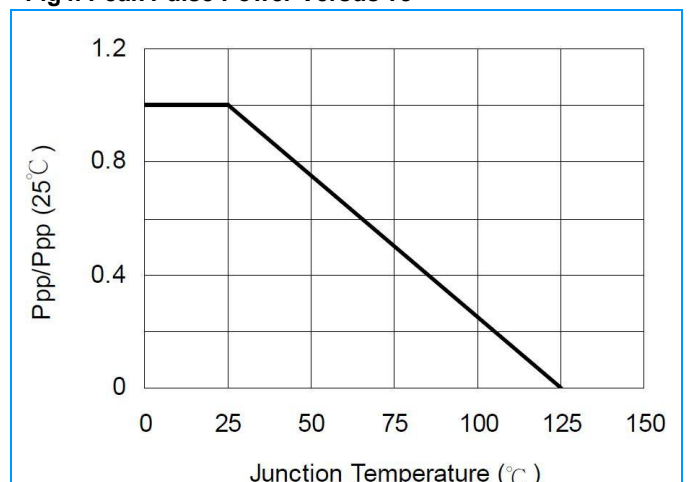
Mechanical Characteristics

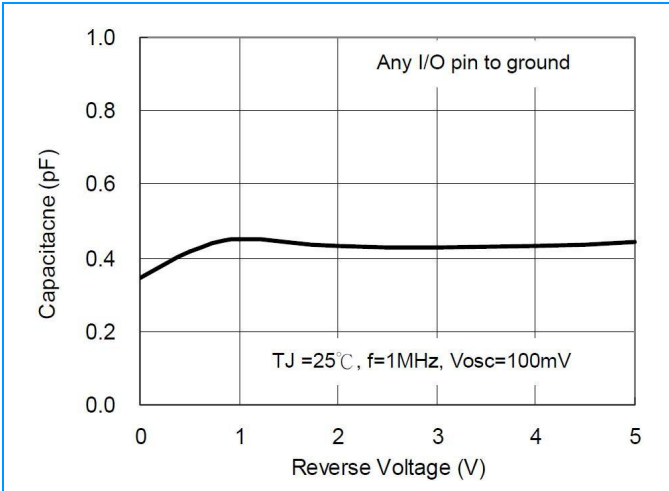
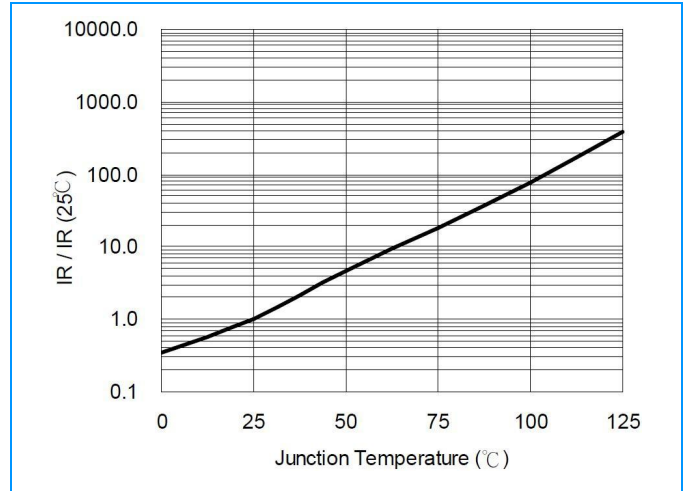
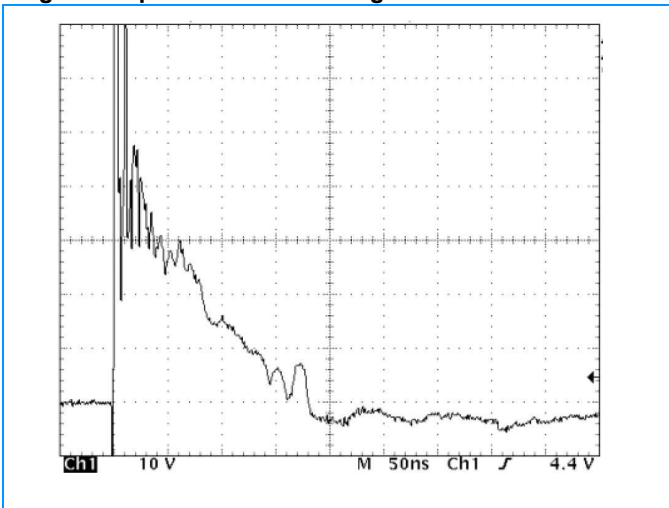
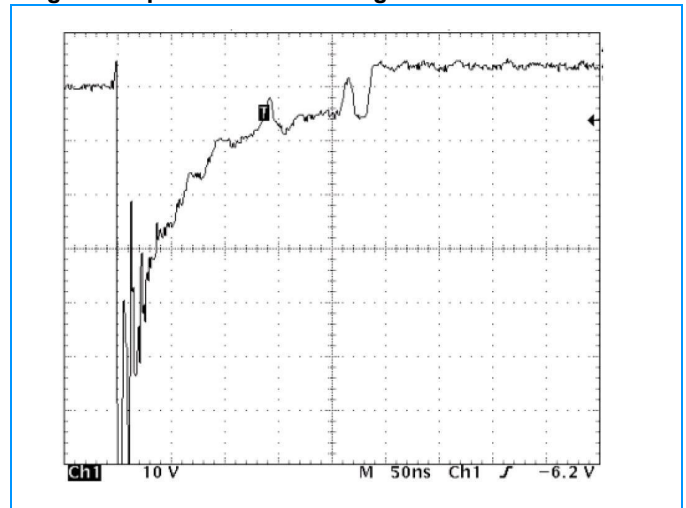
Symbol	Parameter	Value	Units
I _{PP}	Peak Pulse Current (tp=8/20µs waveform)	4	A
T _L	Lead Soldering Temperature	260 (10 sec)	°C
T _J	Operating Junction Temperature Range	-55 to +125	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
T _{OP}	Operating Temperature Range	-55 to +150	°C

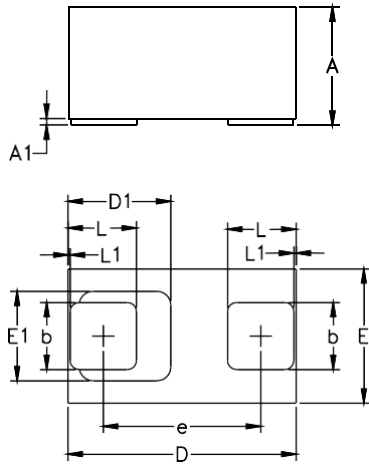
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Electrical Characteristics (T_A = 25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-off Voltage	V _{RWM}	--	--	--	5	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	6	8	--	V
Reverse Leakage Current	I _R	V _{RWM} = +/-5V	--	--	100	nA
Junction Capacitance ⁽¹⁾	C _J	V _R = 0V, f = 1MHz	--	0.35	0.5	pF
Clamping Voltage ⁽¹⁾	V _C	TLP=16A or ESD=8KV	--	15	--	V
Clamping Voltage ⁽¹⁾	V _C	I _{PP} = 1A , t _p = 8/20μs	--	8	--	V
		I _{PP} = 4A , t _p = 8/20μs	--	11	--	V

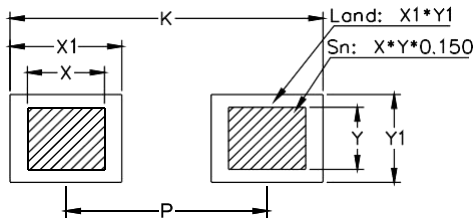
Note: (1) Guaranteed by design.

Characteristic Curves
Fig1. 8/20 us Pulse Waveform

Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

Fig3. Power Dissipation Versus Pulse Time

Fig4. Peak Pulse Power Versus T_J


Characteristic Curves (Continue)
Fig5. Typical Junction Capacitance

Fig6. Reverse Leakage Current Versus TJ

Fig7. Clamped +8 kV ESD Voltage Waveform

Fig8. Clamped -8 kV ESD Voltage Waveform


SE05N6C01GZ
DFN1006 Package Outline & Dimensions


Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.450	0.550	0.018	0.022
A1	0.010	0.070	0.000	0.003
D	0.950	1.050	0.037	0.041
E	0.550	0.650	0.022	0.026
D1	0.450 REF		0.018 REF	
E1	0.400 REF		0.016 REF	
b	0.275	0.325	0.011	0.013
e	0.675	0.725	0.027	0.029
L	0.275	0.325	0.011	0.013
L1	0.010 REF		0.000 REF	

Soldering Footprint


Symbol	Millimeters	Inches
K	1.4±0.05	0.055±0.002
P	0.9±0.025	0.035±0.001
X	0.354±0.025	0.014±0.001
Y	0.283±0.025	0.011±0.001
X1	0.5±0.025	0.020±0.001
Y1	0.4±0.025	0.016±0.001